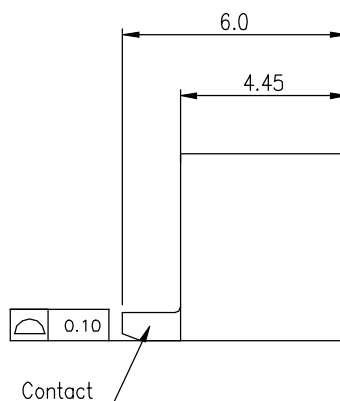
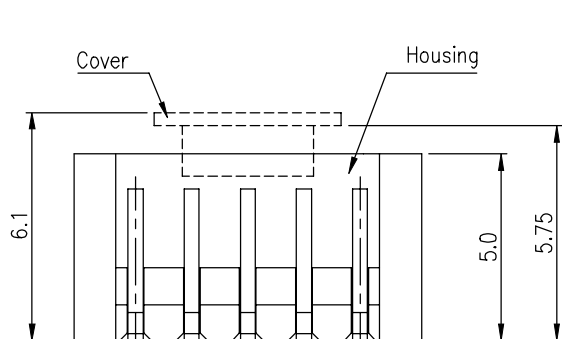


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



NOTES:

1. MATERIAL:
 - 1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP. UL94V-0 .
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
2. FINISH:
 - 2.1 CONTACT: 50~100u" NICKEL UNDERPLATING OVERALL. 1:GOLD FLASH PLATING(1~3u") OVERALL. L:100~200u" TIN PLATING ON SOLDER TAILS, N:100~200u" PURE TIN(MATT TIN)PLATING OVERALL.
 - 2.2 SOLDER: 50~100u" NICKEL UNDERPLATING OVERALL. 1:GOLD FLASH PLATING(1~3u") OVERALL. L:100~200u" TIN PLATING ON SOLDER TAILS, N:100~200u" PURE TIN(MATT TIN)PLATING OVERALL.
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-50289-XXXX-XXX
5. PACKAGE PLS. REFER TO 50293-XXXX-TRP
6. PART NUMBER

P/N LEGEND

50481-XXX X X-ATX

CTKS	XXX	COLOR	COVER	PACKAGE
	AT1	BLACK	WITH COVER	50481-XXXXX-U-TRP

PACKING

- 0:TAPE & REEL
- 1:TUBE
- 7:TAPE & REEL WITH COVER
- 8:TUBE WITH COVER

- PLATING
- L:LEAD FREE (PURE TIN)
- N:MATT TIN
- 1:G/F OVERALL

CKT	Dim A	Dim B	Dim C	Dim D
2	1.5	4.8	3.7	3.3
3	3.0	6.3	5.2	4.8
4	4.5	7.8	6.7	6.3
5	6.0	9.3	8.2	7.8
6	7.5	10.8	9.7	9.3
7	9.0	12.3	11.2	10.8
8	10.5	13.8	12.7	12.3
9	12.0	15.3	14.2	13.8
10	13.5	16.8	15.7	15.3
11	15.0	18.3	17.2	16.8
12	16.5	19.8	18.7	18.3
13	18.0	21.3	20.2	19.8
14	19.5	22.8	21.7	21.3
15	21.0	24.3	23.2	22.8
16	22.5	25.8	24.7	24.3
17	24.0	27.3	26.2	25.8
18	25.5	28.8	27.7	27.3
19	27.0	30.3	29.2	28.8
20	28.5	31.8	30.7	30.3

QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Ding,shuqin DATE 22/11/11		TITLE 1.5mm WTB Wafer Conn. SMT S/T Type			
	CHECKED BY Lu, jing quan DATE 22/11/11			APPROVED BY hsieh,fu yu DATE 22/11/11		
	UNITS mm				SIZE A4	RFQ NO. NA
	SCALE 1:1			SHEET NO. 1 OF 1	REV A	DWG NO. 50481-XXXXX-ATX